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**APPLICATION FOR LETTERS PATENT**

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**ELECTRONIC DEVICE WORKPIECE PROCESSING  
APPARATUS AND METHOD OF COMMUNICATING SIGNALS  
WITHIN AN ELECTRONIC DEVICE WORKPIECE PROCESSING  
APPARATUS**

**EL4658553**

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1       **ELECTRONIC DEVICE WORKPIECE PROCESSING APPARATUS**  
2       **AND METHOD OF COMMUNICATING SIGNALS WITHIN AN**  
3       **ELECTRONIC DEVICE WORKPIECE PROCESSING APPARATUS**

4       **TECHNICAL FIELD**

5       The present invention relates to an electronic device workpiece  
6       processing apparatus and method of communicating signals within an  
7       electronic device workpiece processing apparatus.

8       **BACKGROUND OF THE INVENTION**

9       It is preferred in the semiconductor and related arts to utilize  
10      large wafers for fabrication of integrated circuits and other devices.  
11      Large wafers are preferred inasmuch as an increased number of chips  
12      can be fabricated from larger workpieces. As the size of the wafers  
13      continues to increase as processing techniques are improved, additional  
14      processing obstacles are presented.

15      For example, it is typically preferred to provide a substantially  
16      uniform temperature across the surface of wafers being processed  
17      because changes in temperature can influence device fabrication. Wafers  
18      of increased diameters and surface areas experience increased  
19      temperature fluctuations at various locations on the workpiece. In  
20      particular, a partial vacuum is typically used to pull small diameter  
21      wafers into direct thermal contact with a hot plate. Such processing  
22      methods facilitate substrate temperature control because the substrate  
23      temperature is closely associated to the temperature of the hot plate.  
24      Fabrication of small sub-micron devices upon larger diameter

1 semiconductor wafers or workpieces requires minimal backside  
2 contamination. As such, contact of the workpiece with the hot plate  
3 is not typically possible. Large workpieces are processed in conventional  
4 operations upon spacers or pins that position the workpiece  
5 approximately 0.1 millimeters above the hot plate surface. Such spacing  
6 intermediate a chuck or hot plate and the workpiece can result in  
7 temperature fluctuations across the surface of the workpiece.

8 The utilization of specific materials for processing large workpieces  
9 in small geometry applications presents numerous obstacles. Absolute  
10 workpiece temperature and workpiece temperature uniformity are  
11 parameters which are closely monitored during wafer and workpiece  
12 fabrication to provide critical dimension (CD) control. Chemically  
13 amplified resists are often utilized in deep ultraviolet (DUV) lithography  
14 in small micron geometries (eg., 0.25 microns and below). Chemically  
15 amplified resists are particularly temperature dependent further increasing  
16 the importance of temperature control and monitoring. Some thermal  
17 resist processing steps require process windows ranging from 1-2 degrees  
18 centigrade down to a few tenths of a degree centigrade. Meteorology  
19 that is four to ten times more precise than conventional process  
20 equipment is typically utilized to provide thermal performance  
21 measurements to 0.1 degrees centigrade.

22 One approach has disclosed the use of temperature sensors across  
23 a surface of the wafer to provide temperature mapping of the  
24 workpiece during processing. Platinum foil and copper leads are utilized

1 to electrically connect the temperature sensors. With the use of  
2 numerous temperature sensors across an entire workpiece surface,  
3 numerous wires are required for coupling and monitoring. Such  
4 numerous wired connections can break and/or adversely impact  
5 processing of the workpiece or the temperature measurements taken of  
6 the surface of the workpiece. Some temperature sensors require four  
7 leads per sensor further impacting the processing and temperature  
8 monitoring of the workpieces.

9 An improved method of providing temperature information is  
10 disclosed in U.S. Patent Application Serial No. 09/032,184, entitled  
11 "Electronic Device Workpieces, Methods of Semiconductor Processing and  
12 Methods of Sensing Temperature of an Electronic Device Workpiece",  
13 filed February 27, 1998, naming Dr. Salman Akram and David R.  
14 Hembree as inventors, assigned to the assignee hereof, and incorporated  
15 herein by reference.

16 There exists a need to provide additional improvements for  
17 monitoring of processing of workpieces.

## 18 19 SUMMARY OF THE INVENTION

20 The invention provides electronic device workpiece processing  
21 apparatuses, and methods of communicating signals within an electronic  
22 device workpiece processing apparatus. Exemplary electronic device  
23 workpieces include production workpieces (e.g., silicon wafers) and  
24 calibration wafers.

1 One aspect of the invention provides an electronic device  
2 workpiece processing apparatus including a chuck, intermediate member  
3 and an electronic device workpiece. The chuck includes an electrical  
4 interconnect configured to conduct signals within the chuck. The  
5 intermediate member is configured to conduct signals intermediate  
6 opposing surfaces of the intermediate member. The electronic device  
7 workpiece includes one or more sensors. An exemplary sensor  
8 comprises a resistance temperature device (RTD) configured to provide  
9 process signals containing process information regarding the electronic  
10 device workpiece processing apparatus. A data gathering device or  
11 recorder can be provided to record process information generated by the  
12 electronic device workpiece processing apparatus. The chuck and  
13 intermediate member are configured to communicate the process signals  
14 intermediate the sensor and the data gathering device.

15 According to another aspect of the invention, an electronic device  
16 workpiece processing apparatus includes a workpiece holder. Exemplary  
17 workpiece holders include a chuck and an intermediate member. The  
18 workpiece holder is adapted to receive an electronic device workpiece  
19 and includes an electrical coupling configured to electrically couple with  
20 an electrical coupling of a received electronic device workpiece. The  
21 workpiece holder is adapted for communication of signals between the  
22 electronic device workpiece and the workpiece holder.

23 The present invention also provides methods of communicating  
24 signals within an electronic device workpiece processing apparatus.

1 According to one method, a workpiece holder is coupled with an  
2 electronic device workpiece and a signal can be communicated through  
3 the workpiece holder. The communicated signals preferably contain  
4 process information.

5 Another aspect of the invention provides a method comprising  
6 electrically coupling a sensor of an electronic device workpiece with a  
7 workpiece holder configured to receive the workpiece. The workpiece  
8 holder is configured to communicate signals generated using the sensor.

9 Yet another aspect of the present invention provides a method  
10 comprising communicating signals intermediate circuitry of an electronic  
11 device workpiece and circuitry of a workpiece holder configured to  
12 receive the electronic device workpiece.

### 13 14 BRIEF DESCRIPTION OF THE DRAWINGS

15 Preferred embodiments of the invention are described below with  
16 reference to the following accompanying drawings.

17 Fig. 1 is an isometric view illustrating one embodiment of an  
18 electronic device workpiece processing apparatus.

19 Fig. 2 is a cross-sectional view taken along line 2-2 of the  
20 electronic device workpiece processing apparatus of Fig. 1.

21 Fig. 3 is a cross-sectional view of another embodiment of an  
22 electronic device workpiece processing apparatus.

23 Fig. 4 is an isometric view of a pogo plug of the chuck depicted  
24 in Fig. 3.

1 Fig. 5 is an isometric view of the chuck depicted in Fig. 3.

2 Fig. 6 is a cross-sectional view of another embodiment of an  
3 electronic device workpiece processing apparatus.

4 Fig. 7 is a cross-sectional view of a sensor configuration of an  
5 electronic device workpiece.

6 Fig. 8 is a cross-sectional view of another sensor configuration of  
7 an electronic device workpiece.

8 Fig. 9 is a cross-sectional view of one embodiment of an electrical  
9 interconnect within a chuck of an electronic device workpiece processing  
10 apparatus.

11 Fig. 10 is a cross-sectional view of the electrical interconnect of  
12 Fig. 9 coupled with a calibration workpiece.

13 Fig. 11 is a cross-sectional view of another embodiment of an  
14 electrical interconnect of a chuck.

15 Fig. 12 is a cross-sectional view of yet another embodiment of an  
16 electrical interconnect of a chuck.

17  
18 **DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS**

19 This disclosure of the invention is submitted in furtherance of the  
20 constitutional purposes of the U.S. Patent Laws "to promote the  
21 progress of science and useful arts" (Article 1, Section 8).

22 Referring to Fig. 1, an embodiment of an electronic device  
23 workpiece processing apparatus 10 is illustrated. The depicted  
24 apparatus 10 includes a workpiece holder 12 adapted to couple with or

1 receive an electronic device workpiece 20. Exemplary workpiece  
2 holders 12 include a chuck 40 as shown in Fig. 1 and an intermediate  
3 member described below. Exemplary electronic device workpieces  
4 include calibration workpieces and production workpieces.

5 Workpiece holder 12 includes an electrical coupling (not illustrated  
6 in Fig. 1) configured to electrically connect with an electrical coupling  
7 of electronic device workpiece 20. Connection of circuitry including  
8 electrical couplings of electronic device workpiece 20 and workpiece  
9 holder 12 permits communication of signals between electronic device  
10 workpiece 20 and workpiece holder 12. Workpiece holder 12 is  
11 configured to receive and conduct or communicate signals.

12 Electronic device workpiece 20 comprises a calibration workpiece  
13 in the presently described embodiment. Production workpieces typically  
14 undergo processing from which subsequent devices are formed.  
15 Exemplary production electronic device workpieces include semiconductor  
16 wafers, glass or quartz substrates for flat panel or field emission display  
17 devices, etc. Typical production workpieces are processed and  
18 subsequently utilized to form products used in a variety of electronic  
19 devices. Calibration and production electronic device workpieces can  
20 comprise silicon, glass, quartz or other materials.

21 Workpiece holder 12 can be implemented in various configurations.  
22 In the embodiment depicted in Fig. 1, workpiece holder 12 is  
23 implemented as a chuck 40. Chuck 40 is configured to receive  
24



1 electronic device workpiece 20 and preferably compatible with processing  
2 of electronic device workpiece 20.

3 In the depicted embodiment, electronic device workpiece 20  
4 comprises a calibration workpiece. Workpiece 20 includes opposing  
5 surfaces 21, 22 (only surface 21 is shown in Fig. 1). A plurality of  
6 sensors 23 are borne by or provided adjacent first surface 21 of  
7 workpiece 20. Sensors 23 are configured to sense a process condition  
8 within apparatus 10 and generate and output process signals  
9 corresponding to the sensing. Exemplary process signals contain  
10 information regarding processing of a workpiece.

11 The depicted sensors 23 comprise resistance temperature devices  
12 (RTD). The information within the process signals can comprise  
13 temperature information corresponding to sensed temperatures at plural  
14 positions across surface 21 of workpiece 20.

15 In a preferred embodiment, sensors 23 comprising resistance  
16 temperature devices individually include plural electrical connections.  
17 Such resistance temperature devices include four electrical connections  
18 providing two connections for voltage monitoring and two connections  
19 for current monitoring. This configuration provides cancellation or  
20 minimization of wire resistances of connections to sensors 23.

21 In the embodiment depicted in Fig. 1, chuck 40 is coupled with  
22 a data gathering device or data recorder 14. Data gathering device 14  
23 is configured to couple with an electrical interconnect of chuck 40 and  
24 receive process signals through chuck 40 outputted from plural

1 sensors 23 provided upon workpiece 20. One embodiment of data  
2 gathering device 14 comprises a ClientPro MTR computer available from  
3 Micron Electronics, Inc. utilizing a Pentium™ processor.

4 Data gathering device 14 is configured to receive and process  
5 signals provided by sensors 23 and corresponding to processing  
6 conditions of workpiece 21. Alterations to processing conditions of  
7 apparatus 10 can be changed responsive to reception of process signals  
8 within device 14.

9 Electronic device workpiece 20 is held by chuck 40 with the use  
10 of a vacuum or mechanical coupling in exemplary embodiments. The  
11 depicted chuck 40 includes a lip 52 configured to receive and maintain  
12 electronic workpiece device 20 in a desired position relative to  
13 chuck 40.

14 Referring to Fig. 2, the depicted chuck 40 includes a surface 39  
15 and an opposing surface 41. Chuck 40 also includes circuitry  
16 comprising a plurality of electrical interconnects 44 and plural electrical  
17 couplings 45 adjacent surface 41. Electrical interconnects 44 are  
18 configured to connect with or include respective electrical couplings 45  
19 of chuck 40. In addition, electrical interconnects 44 are configured to  
20 conduct or communicate signals within and through chuck 40. In the  
21 depicted embodiment, electrical interconnects 44 are configured to  
22 conduct or communicate signals intermediate surfaces 39, 41 of  
23 chuck 40.

1 The depicted electrical interconnects 44 comprise pogo pins which  
2 are available from Rika Denshi America, Inc. and have product  
3 designation RM-500 Series. Electrical interconnects 44 of other  
4 configurations can be utilized.

5 Calibration workpiece 20 is shown received within chuck 40 in  
6 Fig. 2. Lip 52 is operable to define a compartment for reception of  
7 electronic device workpiece 20. Surfaces 21, 22 of electronic device  
8 workpiece 20 are illustrated in Fig. 2. A plurality of sensors 23, such  
9 as resistance temperature devices, are shown provided or fabricated upon  
10 surface 21 of electronic device workpiece 20. In the depicted  
11 embodiment, an insulative protective layer 28 is shown formed over  
12 sensors 23. Layer 28 can comprise glass or other suitable material for  
13 protecting sensors 23.

14 One exemplary electronic device workpiece 20 is described in the  
15 patent application having Serial No. 09/032,184, filed February 27, 1998,  
16 and cited above. Such a workpiece 20 includes circuitry comprising  
17 electrical couplings 24, vias 25 and connections 27 corresponding to  
18 respective sensors 23.

19 Connections 27 comprise conductive traces in the described  
20 embodiment and are configured to couple sensors 23 with respective  
21 vias 25. Vias 25 extend intermediate surfaces 21, 22 of electronic  
22 device workpiece 20. Vias 25 preferably include a conductive material  
23 to electrically couple surfaces 21, 22 of workpiece 20. In a preferred  
24 embodiment, the conductive material in vias 25 is electrically isolated

1 from electronic workpiece 20. For example, an insulator or dielectric  
2 layer around the via conductor can be utilized.

3 Electrical couplings 24 are adjacent or borne by surface 22 of  
4 electronic device workpiece 20. Electrical couplings 24 comprise bond  
5 or land pads of electronic device workpiece 20 and correspond to  
6 respective sensors 23 and vias 25. Further, electrical couplings 24 are  
7 preferably configured to provide electrical connection of sensors 23 with  
8 electrical couplings of chuck 40 and an intermediate member (if  
9 provided) as described below.

10 Electrical couplings 45 are spring loaded and configured to  
11 protrude slightly above surface 41 of chuck 40. Electrical couplings 45  
12 of chuck 40 are configured or adapted to couple with electrical  
13 couplings 24 of electronic device workpiece 20. Positioning or reception  
14 of electronic device workpiece 20 upon chuck 40 slightly depresses  
15 electrical couplings 45 of pogo pins or electrical interconnects 44 in the  
16 described embodiment. Electrical connection is established intermediate  
17 electrical couplings 24 of device 20 and electrical couplings 45 of  
18 chuck 40.

19 Following connection of electrical couplings 24, 45, process signals  
20 from data gathering device 14 can be applied to sensors 23 via wire 13,  
21 electrical interconnect 44, electrical couplings 24, 45 and  
22 connections 25, 27. In addition, signals outputted from sensors 23 can  
23 be conducted via connections 25, 27, electrical couplings 24, 45,  
24 electrical interconnect 44, and wire 13 to data gathering device 14.

1 The depicted pogo pins are configured to remain within chuck 40 during  
2 normal production use or processing of production electronic device  
3 workpieces in one embodiment of the invention.

4 Workpiece holder 12, as depicted in Fig. 2, includes a plurality  
5 of vacuum channels or chambers 49 extending intermediate  
6 surfaces 39, 41. Vacuum chambers 49 are coupled with a vacuum  
7 source 51 in a preferred embodiment. Vacuum chambers 49 are  
8 configured to receive a vacuum to couple a received electronic device  
9 workpiece 20 with workpiece holder 12. Mechanical devices such as  
10 clamps are utilized in other embodiments to attach or couple  
11 workpiece 20 with workpiece holder 12.

12 Following coupling of the circuitry of calibration workpiece 20 with  
13 the circuitry of workpiece holder 12, process signals can be  
14 communicated intermediate sensors 23 and data gathering device 14.  
15 Thereafter, the coupling of respective circuitry of workpiece 20 and  
16 workpiece holder 12 can be broken and another calibration workpiece  
17 or production workpiece can be coupled with workpiece holder 12.

18 Referring to Fig. 3, an alternative embodiment of electronic device  
19 workpiece processing apparatus 10 is illustrated. The depicted  
20 processing apparatus 10 includes a workpiece holder 12 comprising an  
21 insert or intermediate member 60. Intermediate member 60 is also  
22 referred to as an insert or interposer. The depicted intermediate  
23 member 60 is adapted to couple with chuck 40, and receive and couple  
24 with electronic device workpiece 20. Intermediate member 60 is

preferably configured to communicate signals intermediate chuck 40 and electronic device workpiece 20.

Intermediate member 60 preferably comprises a nonconductive material which is compatible with a fabrication environment. Intermediate member 60 includes opposing surfaces 61, 62 and circuitry comprising at least one electrical interconnect 64 and plural electrical couplings 65, 66. Electrical interconnect 64 is configured to electrically couple opposing surfaces 61, 62 of intermediate member 60. In addition, electrical interconnect 64 is configured to couple circuitry of workpiece 20 and circuitry of chuck 40. Surface 61 of intermediate member 60 is configured to face a received electronic device workpiece 20. Surface 62 of intermediate member 60 is configured to face chuck 40 during processing of electronic device workpieces 20.

Intermediate member 60 is configured to receive electronic device workpiece 20 having electrical couplings 24. In addition, intermediate member 60 is configured to couple with chuck 40 having electrical couplings 45. Electrical interconnects 64 are configured to electrically connect electrical couplings 24 of electronic device workpiece 20 with electrical couplings 45 of chuck 40. The depicted electrical interconnects 64 comprise double-ended probes or pogo pins which are also available from Rika Denshi America, Inc. and have product designation B1052 Series Probes. Other suitable probes include B1080-C3 Low Profile Probes and the B1303-C3 or B1316-C3 Ball Grid Probes. Electrical interconnects 64 of other configurations can be utilized.

1 The depicted intermediate member includes a lip 63 configured to  
2 receive electronic device workpiece 20. Chuck 40 includes lip 52  
3 configured to receive intermediate member 60.

4 In the depicted embodiment, mechanical devices such as clamps  
5 can be utilized to couple or maintain electronic device workpiece 20  
6 with surface 61 of intermediate member 60. Further, a vacuum is  
7 utilized in the illustrated embodiment to couple intermediate member 60  
8 with chuck 40. The depicted chuck 40 includes plural chuck vacuum  
9 channels or chambers 49. Vacuum channels 49 are in fluid  
10 communication with openings 53 at surface 41 of chuck 40. Vacuum  
11 channels or chambers 49 are configured to couple with a vacuum  
12 source 51 and receive a vacuum to couple intermediate member 60  
13 relative to chuck 40. In other embodiments, intermediate member 60  
14 is received and maintained within chuck 40 by mechanical fasteners such  
15 as clamps. In addition, a vacuum can be utilized in other arrangements  
16 to couple workpiece 20 with intermediate member 60.

17 An alternative configuration of intermediate member 60 includes  
18 utilization of a copper film/polyamide tape having conductive microbumps  
19 to provide electrical connection of sensors 23 and electrical couplings 45  
20 of chuck 40. An exemplary tape is available from Nitto Denko  
21 America, Inc.

22 Referring to Figs. 3 and 4, the depicted chuck 40 includes a  
23 plurality of electrical couplings 45. Electrical couplings 45 are embodied  
24 as pogo plugs 47 in the presently described embodiment. The depicted

1 pogo plugs 47 individually include an insulator 50 provided about  
2 conductive electrical coupling 45. Exemplary materials of insulator 50  
3 include plastic, glass, ceramic, Teflon, and Torlon. Pogo plugs 47 can  
4 be provided within a plurality of vias 48 formed within chuck 40.  
5 Wires 13 are connected with electrical couplings 45 of pogo plugs 47  
6 and data gathering device 14.

7 Referring to Fig. 5, details of chuck 40 are illustrated. Electrical  
8 couplings 45 are shown adjacent surface 41 of chuck 40. Insulators 50  
9 of pogo plugs 47 are shown to isolate conductive electrical couplings 45  
10 from chuck 40. In addition, openings 53 of vacuum channels or  
11 chambers 49 are visible within surface 41. Lip 52 surrounds the  
12 periphery of chuck 40 in the illustrated embodiment and is configured  
13 to receive intermediate member 60 as previously described.

14 Referring again to Fig. 3, reception of electronic device  
15 workpiece 20 upon surface 61 of intermediate member 60 slightly  
16 depresses electrical couplings 65 of pogo pins 64 establishing an  
17 electrical connection intermediate electrical couplings 24, 65. Similarly,  
18 placement of intermediate member 60 within chuck 40 slightly depresses  
19 electrical couplings 66 of pogo pins 64 establishing electrical conduction  
20 intermediate electrical couplings 45, 66.

21 In the described embodiment, intermediate member 60 is  
22 configured to temporarily receive electronic device workpiece 20.  
23 Following processing of electronic device workpiece 20, workpiece 20 can  
24 be removed from intermediate member 60. Also, chuck 40 is



1 configured to temporarily receive intermediate member 60 in the  
2 described embodiment. Following production or processing of electronic  
3 device workpieces 20, intermediate member 60 can be removed from  
4 chuck 40.

5 One advantage of the embodiment described with reference to  
6 Fig. 3, is the provision of a clean production chuck 40 having no  
7 moving parts. In addition, chuck 40 is isolated to a greater extent  
8 from the processing environment utilized to fabricate or process  
9 electronic device workpieces 20. Utilization of intermediate member 60  
10 provides processing of electronic device workpiece 20 apart from  
11 chuck 40. Such minimizes exposure of chuck 40 to processing materials  
12 utilized during fabrication processes.

13 According to one processing methodology, calibration workpiece 20  
14 is received within intermediate member 60, and intermediate member 60  
15 placed upon chuck 40. Following sensing of process conditions using  
16 sensors 23, calibration workpiece 20 is removed from intermediate  
17 member 60. Thereafter, production electronic device workpieces are  
18 individually placed within intermediate member 60 and processing of  
19 such workpieces occurs in mass.

20 Referring to Fig. 6, another embodiment of an electronic  
21 workpiece processing apparatus 10 according to the present invention is  
22 illustrated. Workpiece holder 12 depicted in Fig. 6 comprises a  
23 chuck 40 configured to receive plural electronic device workpieces. In  
24 particular, chuck 40 is configured to receive a calibration workpiece 20

1 and a production workpiece 80. Lip 52 of chuck 40 has been vertically  
2 extended in the embodiment illustrated in Fig. 6 to accommodate  
3 reception of plural electronic device workpieces. Utilization of the  
4 configuration of apparatus 10 of Fig. 6 enables processing of production  
5 workpieces 80 while monitoring processing conditions using calibration  
6 workpiece 20.

7 Calibration workpiece 20 includes plural sensors 23 and  
8 corresponding connections 25, 27 and electrical coupling 24 although only  
9 one construction is labelled as such in Fig. 6. The calibration  
10 workpiece 20 illustrated in Fig. 6 additionally includes plural through  
11 holes or vacuum chambers 26 passing intermediate surfaces 21, 22.  
12 Plural through holes 26 are preferably provided within calibration  
13 workpiece 20 although only one such through hole is illustrated in  
14 Fig. 6.

15 The depicted chuck 40 comprises plural vacuum channels or  
16 chambers 49, 55 intermediate surfaces 39, 41 of chuck 40. Vacuum  
17 channels or chambers 49 allow application of a vacuum to calibration  
18 workpiece 20 which pulls calibration workpiece 20 toward chuck 40.  
19 Vacuum chambers 55 and through holes 26 permit application of a  
20 vacuum to production workpiece 80 which pulls production workpiece 80  
21 toward calibration workpiece 20 and chuck 40.

22 In particular, vacuum channels or chambers 49, 55 are configured  
23 to couple with an external vacuum source 51 at positions adjacent  
24 surface 39 of chuck 40. Vacuum source 51 is configured to provide a

1 calibration wafer hold-down vacuum to chamber 54 using a supply  
2 line 56. In addition, the illustrated vacuum source 51 is configured to  
3 provide a production wafer hold-down vacuum to vacuum channel or  
4 chambers 26, 55 and production wafer 80 via connection 57. As  
5 illustrated, through holes 26 of calibration wafer 20 are configured to  
6 align with vacuum chambers 55 of chuck 40. Application of hold-down  
7 vacuums to channels or chambers 26, 49, 55 operate to couple the  
8 respective calibration workpiece 20 and production workpiece 80 with  
9 chuck 40.

10 In an alternative embodiment, mechanical devices are utilized to  
11 couple calibration workpiece 20 and production workpiece 80 with  
12 chuck 40.

13 The depicted chuck 40 includes an electrical interconnect 44 and  
14 an electrical coupling 45 configured to meet or couple with electrical  
15 coupling 24 of calibration workpiece 20. In the depicted arrangement,  
16 electrical interconnect 44 comprises a pogo pin. Wire connection 13  
17 operates to couple electrical interconnect 44 with data gathering  
18 device 14. In the depicted embodiment, electrical interconnect 44  
19 comprises circuitry configured to conduct process signals within chuck 40  
20 and intermediate surfaces 39, 41. Data gathering device 14 is  
21 configured to receive the process signals from sensors 23 through  
22 chuck 40 and intermediate member 60.

23 Referring to Fig. 7, an exemplary portion of a calibration  
24 workpiece 20 is illustrated. Sensor 23 comprising a resistance

1 temperature device is shown provided upon surface 21 of calibration  
2 workpiece 20. Via 25 is formed within calibration workpiece 20  
3 intermediate surfaces 21, 22. Via 25 is conductive to permit  
4 communication of process signals. Electrical connection 27 is illustrated  
5 connecting sensor 23 and via 25. In the depicted embodiment, electrical  
6 connection 27 comprises a conductive trace.

7 An insulative dielectric layer 30 is provided about via  
8 conductor 25 in some configurations. Provision of dielectric layer 30  
9 is preferred if workpiece 20 is semiconductive or conductive. Layer 30  
10 is typically not utilized if workpiece 20 comprises a non-conductive  
11 material, such as glass.

12 In the preferred embodiment, a conformal protection layer 28 is  
13 provided over surface 21, sensor 23 and connection 27. Layer 28  
14 operates to protect surface 21, sensor 23 and electrical connection 27  
15 from the processing environment including gasses, chemicals, plasmas, etc.  
16 utilized during processing of the electronic device workpieces. In the  
17 described embodiment, layer 28 comprises glass. The glass may be  
18 sputtered over calibration workpiece 20 including sensors 23, electrical  
19 connections 27 and surface 21.

20 Referring to Fig. 8, a thick protection layer 28 is shown provided  
21 over sensors 23 and electrical connection 27. Layer 28 is preferably  
22 chemically or mechanically polished providing a flat or smooth  
23 surface 29 of layer 28. A polished or flat smooth surface 29 of  
24 layer 28 facilitates vacuum sealing of a production workpiece 80 placed

1 over calibration workpiece 20. In addition, flat smooth surface 29  
2 provides enhanced wearing properties during processing of production  
3 workpieces 80 or exposure of calibration workpiece 20 to process  
4 conditions. A worn or damaged glass layer 28 may be reprocessed to  
5 add more glass or resurfaced to remove defects within the existing glass  
6 layer.

7 Referring to Fig. 9, a portion of another embodiment of chuck 40  
8 configured to receive a calibration workpiece (not illustrated in Fig. 9)  
9 is depicted. Through hole 42 is shown passing intermediate  
10 surfaces 39, 41 of chuck 40. Plural through holes 42 are preferably  
11 provided in chuck 40 although only one such through hole is illustrated  
12 in Fig. 9. An insulative layer (not illustrated in Fig. 9) is preferably  
13 provided if chuck 40 comprises a conductive material. In particular, an  
14 insulative layer can be provided about interconnect 44 or along the  
15 surface of through hole 42 to electrically isolate interconnect 44 from  
16 chuck 40. Such an insulative layer is not typically utilized if chuck 40  
17 is non-conductive.

18 Electrical interconnect 44 comprises a conductive column or wire  
19 in the embodiment depicted in Fig. 9. In particular, the depicted  
20 electrical interconnect 44 comprises a buckle beam or column wire  
21 contact. Electrical interconnect 44 is provided within through hole or  
22 via 42. Electrical interconnect 44 includes electrical couplings 45, 46  
23 which are configured to extend outward from respective surfaces 39, 41  
24

1 of chuck 40 as shown. Column electrical interconnect 44 is configured  
2 to provide electrical coupling with sensors 23.

3 A contact plate 90 is shown adjacent chuck 40 in Fig. 9.  
4 Contact plate 90 includes circuitry 95 configured to provide electrical  
5 connection with electrical couplings 46 of chuck 40. Contact plate 90  
6 includes a land pad or electrical coupling 94 configured for electrical  
7 connection with electrical coupling 46 of column interconnect 44.  
8 Electrical contact plate 90 can comprise a printed circuit board (PCB),  
9 ceramic thick/thin film circuit board in exemplary embodiments.  
10 Circuitry 95 provides electrical connection intermediate surfaces 91, 96  
11 of contact plate 90. Circuitry 95 is coupled with connection 13 and  
12 data gathering device 14.

13 Referring to Fig. 10, an electronic device workpiece comprising a  
14 calibration wafer 20 is shown contacting surface 41 of chuck 40. In  
15 addition, chuck 40 is shown contacting contact plate 90. As illustrated,  
16 placement of calibration workpiece 20 upon chuck 40 and chuck 40  
17 upon plate 90 deflects conductive column 44. In particular, the original  
18 position P of conductive column 44 is represented by a dashed line in  
19 Fig. 10. Placement of calibration workpiece 20 upon chuck 40 and  
20 chuck 40 upon contact plate 90 results in deflection of conductive  
21 column 44 to the illustrated position P' in Fig. 10.

22 In the illustration of Fig. 10, electrical couplings 45, 46 are  
23 provided in a conductive relationship with respective electrical  
24 couplings 24, 94 of calibration workpiece 20 and contact plate 90

1 respectively. Through hole 84 is preferably sized to provide electrical  
2 isolation of conductive column interconnect 44 from chuck 40 when  
3 conductive column 44 is deflected as shown in Fig. 10. In particular,  
4 chuck 40 can comprise a material 43 which is conductive in some  
5 embodiments. Spacing conductive column 44 from material 43 of  
6 chuck 40 provides electrical insulation or isolation of process signals  
7 passing through conductive column electrical interconnect 44 from  
8 chuck 40.

9 In another embodiment, conductive wire interconnect 44 is fixed  
10 via electrical coupling 46 to electrical coupling 94 of contact plate 90.  
11 Electrical coupling 45 of conductive column 44 can thereafter be free  
12 to couple with electrical coupling 24 of calibration workpiece 20.

13 Referring to Fig. 11, another configuration having conductive  
14 column 44 fixed to chuck 40 at an intermediate location of through  
15 hole 84 is illustrated. Both ends of conductive column 44 comprise  
16 respective electrical couplings 45, 46 configured to move or deflect  
17 responsive to coupling with external pads or electrical couplings. In the  
18 depicted embodiment, a securing device 88 is formed within through  
19 hole 84 to fix conductive column 44 at the approximately middle portion  
20 of through hole 84. In exemplary embodiments, securing device 88  
21 comprises epoxy press fit as a disk or plug into through hole 84. In  
22 another embodiment, through hole 84 is filled with epoxy which is  
23 subsequently machined to form securing device 88. Securing device 88  
24 is preferably non-conductive if chuck 40 comprises a conductive material.

Referring to Fig. 12, an alternative configuration is shown providing an encapsulated conductive column wire 44 within through hole 84. An electrically insulating encapsulating material 97, such as an elastomer, can be utilized to encapsulate conductive column 44. Such is preferred wherein chuck 40 comprises a conductive material 43. Encapsulation of conductive column interconnect 44 is utilized to hold conductive column wire 44 within through hole 84 and isolate conductive column 44 from chuck 40. Utilization of an encapsulating material 97 encloses through hole 84 of chuck 40 thereby reducing exposure of chuck 40 to contaminating materials present during processing of electronic device workpieces by apparatus 10.

Other electrical connections can be utilized within chuck 40 and intermediate member 60 of electronic workpiece device processing apparatus 10 in other embodiments. Exemplary connections include Short Contact™ connections available from Johnstech International Corporation and conventional socket type contacts (e.g., spring fingers). Other useable contacts include coil spring, leaf spring and probe needle type contacts and contacts available from Interconnect Devices, Inc. Microspring™ contacts available from FormFactor, Inc. may also be utilized. Other exemplary contacts or pins are described in U.S. Patent No. 5,495,667, incorporated herein by reference. Further, pins can be placed upon land pads of an electronic device workpiece and configured for mating receipt within sockets provided upon chuck 40 or intermediate member 60 of apparatus 10.



1 In compliance with the statute, the invention has been described  
2 in language more or less specific as to structural and methodical  
3 features. It is to be understood, however, that the invention is not  
4 limited to the specific features shown and described, since the means  
5 herein disclosed comprise preferred forms of putting the invention into  
6 effect. The invention is, therefore, claimed in any of its forms or  
7 modifications within the proper scope of the appended claims  
8 appropriately interpreted in accordance with the doctrine of equivalents.  
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